

ABSTRACT OF THE INVENTION

63) A method of joining two microelectronic components using a ternary lead-free solder alloy which consists essentially of a major portion of tin, from 6 wt% to about 15 wt% bismuth and from 2 to 5 wt% silver. The method also produces circuit boards using the ternary solder alloy from either a solder paste or stationary wave of liquid solder.

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